

| L Number | Hits | Search Text | DB | Time stamp |
|----------|---------|--|---|------------------|
| 3 | 14 | (US-6333564-\$ or US-6080932-\$ or US-6114192-\$ or US-6038136-\$ or US-5976912-\$ or US-5557150-\$ or US-5653020-\$).did. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/06/26 15:58 |
| 5 | 2 | ((("6518654") or ("6329220"))).PN. | USPAT | 2004/06/26 15:59 |
| 4 | 7 | (US-6333564-\$ or US-6080932-\$ or US-6114192-\$ or US-6038136-\$ or US-5976912-\$ or US-5557150-\$ or US-5653020-\$).did. | USPAT | 2004/06/26 16:06 |
| 6 | 14 | US-5930603-\$.DID. OR US-5914531-\$.DID. OR US-5293072-\$.DID. OR US-5650593-\$.DID. OR US-6049038-\$.DID. OR US-6225144-\$.DID. OR US-5448114-\$.DID. OR US-5583378-\$.DID. OR US-5708304-\$.DID. OR US-5625222-\$.DID. OR US-6261870-\$.DID. OR US-5604376-\$.DID. OR US-4641176-\$.DID. OR US-6002178-\$.DID. | USPAT | 2004/06/26 16:09 |
| 7 | 4 | ("2570221").PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/06/26 16:09 |
| 8 | 3 | (US-5914531-\$ or US-6114192-\$).did. or (FR-2570221-\$).did. | USPAT; EPO | 2004/06/26 16:17 |
| 9 | 1013170 | mold\$4 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/06/26 16:17 |
| 11 | 51370 | mold\$4 and ((encapsulat\$4 or seal\$4) with (semiconductor or device or die or chip)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/06/26 16:42 |
| 12 | 15351 | (mold\$4 and ((encapsulat\$4 or seal\$4) with (semiconductor or device or die or chip))) and (plural\$6 with (die or semiconducotr or chip or device)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/06/26 16:42 |
| 13 | 1719 | ((mold\$4 and ((encapsulat\$4 or seal\$4) with (semiconductor or device or die or chip))) and (plural\$6 with (die or semiconducotr or chip or device))) and rib | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/06/26 16:42 |
| 14 | 114 | ((mold\$4 and ((encapsulat\$4 or seal\$4) with (semiconductor or device or die or chip))) and (plural\$6 with (die or semiconducotr or chip or device))) and rib) and (mold with rib) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/06/26 16:41 |
| 15 | 91059 | 425/\$.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/06/26 16:41 |
| 16 | 36515 | 425/\$.ccls. and mold\$4 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/06/26 16:41 |
| 17 | 8145 | (425/\$.ccls. and mold\$4) and (die or semiconducotr or chip) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/06/26 16:41 |

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|----|------|---|---|------------------|
| 18 | 1099 | ((425/\$.ccls. and mold\$4) and (die or semiconducotr or chip)) and ((encapsulat\$4 or seal\$4) with (semiconductor or device or die or chip)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/06/26 16:42 |
| 19 | 452 | ((425/\$.ccls. and mold\$4) and (die or semiconducotr or chip)) and ((encapsulat\$4 or seal\$4) with (semiconductor or device or die or chip))) and (plural\$6 with (die or semiconducotr or chip or device)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/06/26 16:42 |
| 20 | 49 | ((425/\$.ccls. and mold\$4) and (die or semiconducotr or chip)) and ((encapsulat\$4 or seal\$4) with (semiconductor or device or die or chip))) and (plural\$6 with (die or semiconducotr or chip or device))) and rib | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/06/26 16:42 |
| 21 | 37 | ((425/\$.ccls. and mold\$4) and (die or semiconducotr or chip)) and ((encapsulat\$4 or seal\$4) with (semiconductor or device or die or chip))) and (plural\$6 with (die or semiconducotr or chip or device))) and rib) not (((mold\$4 and ((encapsulat\$4 or seal\$4) with (semiconductor or device or die or chip))) and (plural\$6 with (die or semiconducotr or chip or device))) and rib) and (mold with rib)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/06/26 16:42 |
| 22 | 5 | (US-5914531-\$ or US-6114192-\$).did. or (US-20010032800-\$ or US-20010026665-\$).did. or (FR-2570221-\$).did. | USPAT; US-PGPUB; EPO | 2004/06/26 16:49 |
| 23 | 1 | (US-5914531-\$).did. | USPAT | 2004/06/26 16:52 |